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**(54) METHOD OF MOUNTING ELECTRONIC COMPONENTS ON DOUBLE-SIDED MOUNTING BOARD**

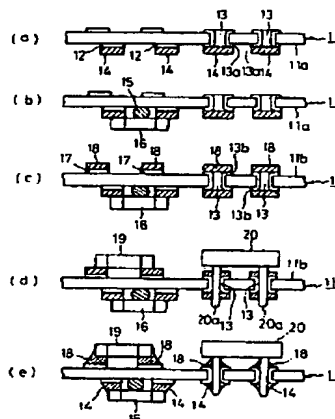
solder cream 14 and 18 may be melted so as to solder each component.

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**(57) Abstract:**

**PURPOSE:** To make it possible to solder components mounted on the surface of a printed board on both sides and a dip component simultaneously by applying solder cream on a soldered section of said component mounted on the surface of said printed board and a land section on a through hole for mounting a dip component simultaneously.

**CONSTITUTION:** A soldered section 12 of a components mounted on the surface of a printed board 11 on one side 11a and a land section 13a, which is one party of a dip component mounting through hole 13, are coated with solder cream 14 based on screen printing, using a metal mask. Then, a surface mounted component 16 is bonded on one side 11a of the printed board 11 in a specified position, using a bonding agent. Solder cream 18 is applied on a land section 13b, which is one party of the through hole 13 based on screen printing, using a metal mask. In succession, a surface mounted component 19 and a dip component 20 are installed to the other side 11b of the printed board 11 in a specified position. The printed board 11 is heated in a heating furnace so that



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